

NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "VCC" represents connection to the +2.5V power plane.
2. The netname "GND" represents connection to the ground plane.



COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY

REVISIONS

REV	DESCRIPTION	DATE	APPROVED
A	ECO 2136070: Initial Release	9/18/2013	NG

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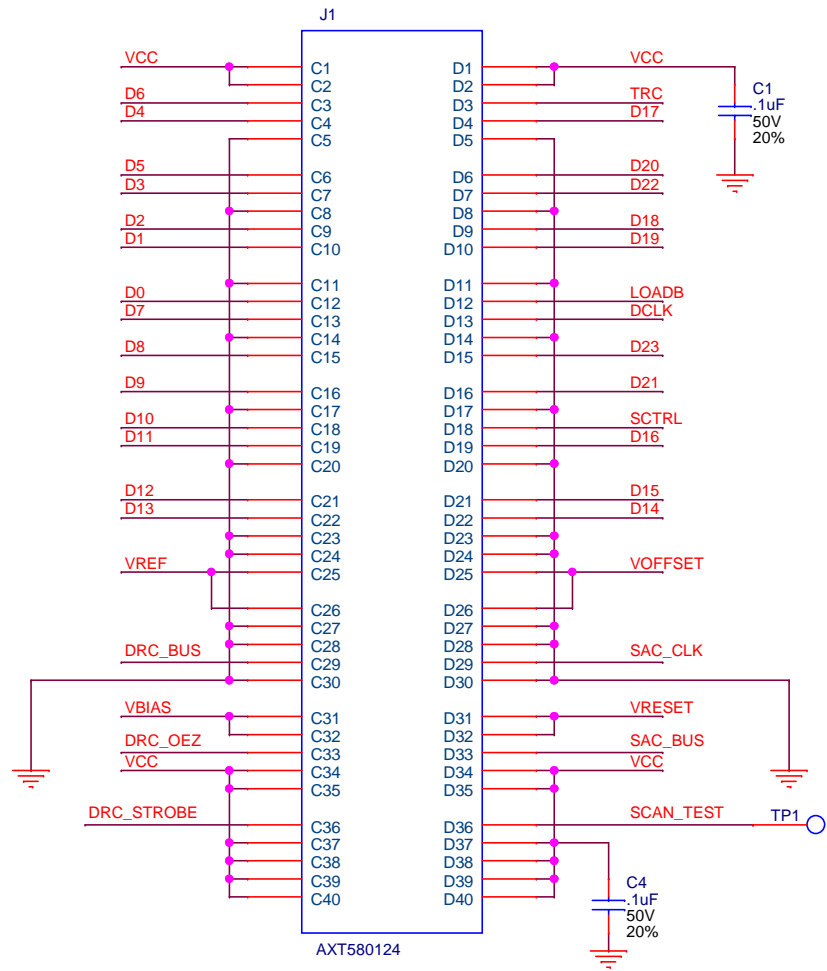
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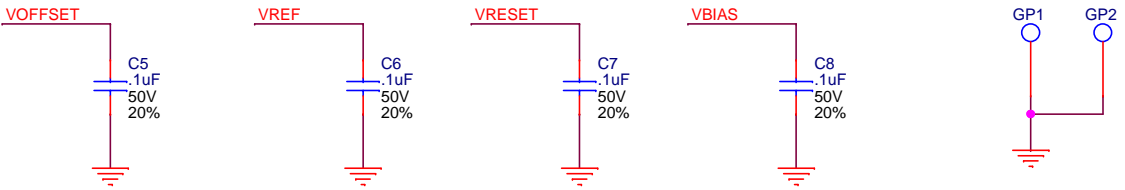
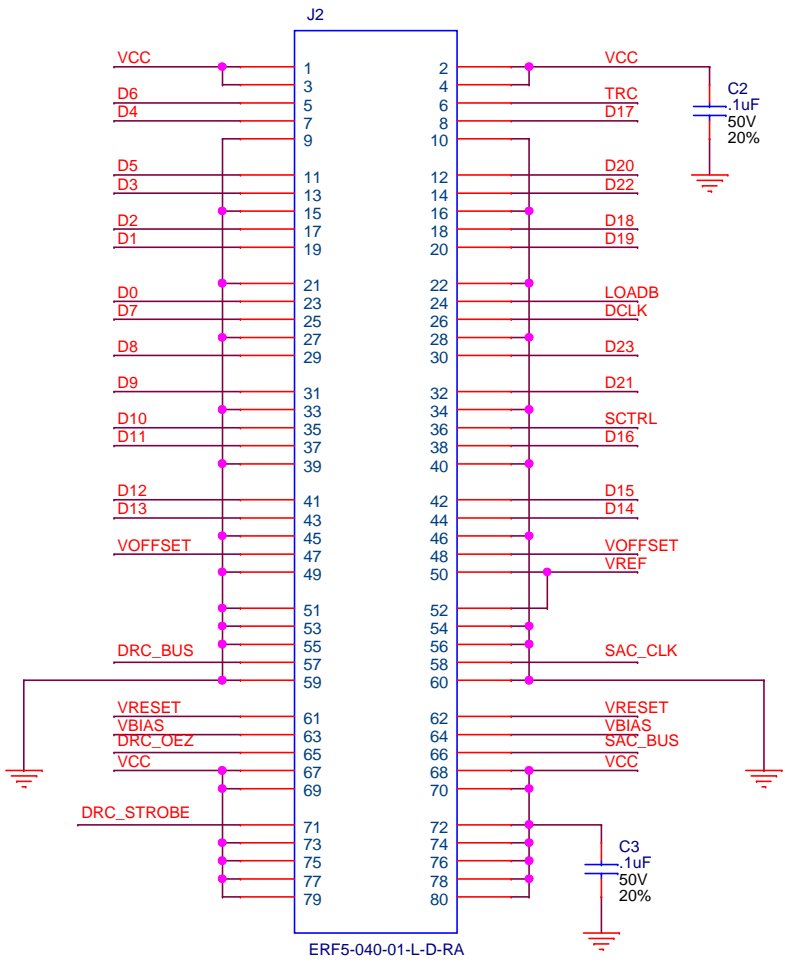
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		ENGR A. NG	09/18/2013			
		APVD Joe Siddall				
		MFG		TITLE ESD, NIRscan s241 DMD Board		
	0314CP	QA				
NEXT ASSY	USED ON					
APPLICATION		SW Allegro Design Entry 16.6		A3	DRAWING NO 2513466	REV A
				SCALE	SHEET 1 of 4	

DMD Connector



Samtec RA



Revision History

Rev. A: ECO 2136070: Initial Release ~ 9/18/2013

TEXAS INSTRUMENTS

DWN
A. Ng

DATE
09/18/2013

ISSUE DATE
09/18/2013

A3

DRAWING NO
2513466

REV
A

SCALE

SHEET 4 OF 4

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